3-V TO 5.5-V SINGLE-CHANNEL RS-232 LINE DRIVER/RECEIVER WITH \pm 15-kV ESD PROTECTION

SLLS348M - JUNE 1999 - REVISED MARCH 2004

- RS-232 Bus-Pin ESD Protection Exceeds ±15 kV Using Human-Body Model (HBM)
- Meets or Exceeds the Requirements of TIA/EIA-232-F and ITU v.28 Standards
- Operates With 3-V to 5.5-V V_{CC} Supply
- Operates Up To 250 kbit/s
- One Driver and One Receiver
- Low Standby Current . . . 1 μA Typical
- External Capacitors . . . 4 × 0.1 μF
- Accepts 5-V Logic Input With 3.3-V Supply
- Alternative High-Speed Pin-Compatible Device (1 Mbit/s)
 - SNx5C3221
- Auto-Powerdown Feature Automatically Disables Drivers for Power Savings
- Applications
 - Battery-Powered, Hand-Held, and Portable Equipment
 - PDAs and Palmtop PCs
 - Notebooks, Subnotebooks, and Laptops
 - Digital Cameras
 - Mobile Phones and Wireless Devices

DB OR PW PACKAGE (TOP VIEW) $\overline{\mathsf{EN}}$ 16 FORCEOFF 15 V_{CC} С1+ Г 2 V+ **∏**3 14∏ GND C1− ¶4 13**∏** DOUT 12 FORCEON C2+ [5 11 DIN C2- []6 V− **∏**7 10 INVALID 9 ROUT RIN L 8

description/ordering information

The MAX3221 consists of one line driver, one line receiver, and a dual charge-pump circuit with ± 15 -kV ESD protection pin to pin (serial-port connection pins, including GND). The device meets the requirements of TIA/EIA-232-F and provides the electrical interface between an asynchronous communication controller and the serial-port connector. The charge pump and four small external capacitors allow operation from a single 3-V to 5.5-V supply. These devices operate at data signaling rates up to 250 kbit/s and a maximum of 30-V/ μ s driver output slew rate.

ORDERING INFORMATION

TA	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	CCOD (DD)	Tube of 80	MAX3221CDB	MA3221C
000 to 7000	SSOP (DB)	Reel of 2000	MAX3221CDBR	MA3221C
−0°C to 70°C	TSSOP (PW)	Tube of 90	MAX3221CPW	MA20040
		Reel of 2000	MAX3221CPWR	MA3221C
	0000 (DD)	Tube of 80	MAX3221IDB	MD00041
4000 1- 0500	SSOP (DB)	Reel of 2000	MAX3221IDBR	MB3221I
−40°C to 85°C	TOCOD (DIA)	Tube of 90	MAX3221IPW	MD20041
	TSSOP (PW)	Reel of 2000	MAX3221IPWR	MB3221I

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



3-V TO 5.5-V SINGLE-CHANNEL RS-232 LINE DRIVER/RECEIVER WITH ±15-kV ESD PROTECTION

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description/ordering information (continued)

Flexible control options for power management are available when the serial port is inactive. The auto-powerdown feature functions when FORCEON is low and FORCEOFF is high. During this mode of operation, if the device does not sense a valid RS-232 signal on the receiver input, the driver output is disabled. If FORCEOFF is set low and EN is high, both the driver and receiver are shut off, and the supply current is reduced to 1 µA. Disconnecting the serial port or turning off the peripheral drivers causes the auto-powerdown condition to occur. Auto-powerdown can be disabled when FORCEON and FORCEOFF are high. With auto-powerdown enabled, the device is activated automatically when a valid signal is applied to the receiver input. The INVALID output notifies the user if an RS-232 signal is present at the receiver input. INVALID is high (valid data) if the receiver input voltage is greater than 2.7 V or less than -2.7 V, or has been between -0.3 V and 0.3 V for less than 30 μs. INVALID is low (invalid data) if the receiver input voltage is between -0.3 V and 0.3 V for more than 30 us. Refer to Figure 5 for receiver input levels.

Function Tables

EACH DRIVER

		INPUTS		OUTPUT	
DIN	FORCEON	FORCEOFF	VALID RIN RS-232 LEVEL	DOUT	DRIVER STATUS
Х	Χ	L	Х	Z	Powered off
L	Н	Н	Х	Н	Normal operation with
Н	Н	Н	X	L	auto-powerdown disabled
L	L	Н	Yes	Н	Normal operation with
Н	L	Н	Yes	L	auto-powerdown enabled
L	L	Н	No	Z	Powered off by
Н	L	Н	No	Z	auto-powerdown feature

H = high level, L = low level, X = irrelevant, Z = high impedance

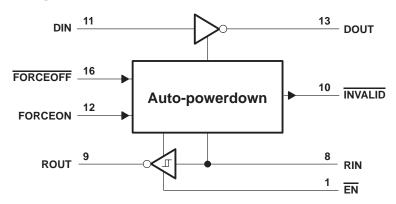
EACH RECEIVER

	INP	PUTS	OUTPUT
RIN	EN	VALID RIN RS-232 LEVEL	ROUT
L	L	Х	Н
Н	L	X	L
Х	Н	X	Z
Open	L	No	Н

H = high level, L = low level, X = irrelevant, Z = high impedance (off), Open = disconnected input or connected driver off



logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC} (see Note 1)	0.3 V to 6 V
Positive output supply voltage range, V+ (see Note 1)	–0.3 V to 7 V
Negative output supply voltage range, V– (see Note 1)	0.3 V to –7 V
Supply voltage difference, V+ – V– (see Note 1)	13 V
Input voltage range, V _I : Driver (FORCEOFF, FORCEON, EN)	0.3 V to 6 V
Receiver	–25 V to 25 V
Output voltage range, V _O : Driver	13.2 V to 13.2 V
Receiver (INVALID)	
Package thermal impedance, θ_{JA} (see Notes 2 and 3): DB package	82°C/W
PW package	108°C/W
Operating virtual junction temperature, T _J	150°C
Storage temperature range, T _{stq}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltages are with respect to network GND.
 - 2. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4 and Figure 6)

				MIN	NOM	MAX	UNIT
	Supply voltage		V _{CC} = 3.3 V	3	3.3	3.6	.,
			V _{CC} = 5 V	4.5	5	5.5	V
V	Driver and central high level input voltage	DIN FORCEOU EN	V _{CC} = 3.3 V	2			V
VIH	Driver and control high-level input voltage	el input voltage DIN, FORCEOFF, FORCEON, EN		2.4			٧
V_{IL}	Driver and control low-level input voltage	DIN, FORCEOFF, FORCEON, EN				0.8	V
٧ı	Driver and control input voltage	DIN, FORCEOFF, FORCEON		0		5.5	V
٧ı	Receiver input voltage			-25		25	V
т.	Operating free air temperature		MAX3221C	0		70	°C
TA	Operating free-air temperature		MAX3221I	-40		85	C

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at V $_{CC}$ = 3.3 V \pm 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V $_{CC}$ = 5 V \pm 0.5 V.



MAX3221

3-V TO 5.5-V SINGLE-CHANNEL RS-232 LINE DRIVER/RECEIVER WITH ±15-kV ESD PROTECTION

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electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

	PARAMETER TEST CONDITIONS			MIN	TYP	MAX	UNIT	
Ц	Input leakage current	FORCEOFF, FORCEON, EN				±0.01	±1	μА
		Auto-powerdown disabled		No load, FORCEOFF and FORCEON at V _{CC}		0.3	1	mA
Icc	Supply current	Powered off	$V_{CC} = 3.3 \text{ V or 5 V},$ $T_{A} = 25^{\circ}\text{C}$	No load, FORCEOFF at GND		1	10	
	Supply current	Auto-powerdown enabled	14 - 20 0	No load, FORCEOFF at V _{CC} , FORCEON at GND, All RIN are open or grounded		1	10	μΑ

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V.

DRIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

	PARAMETER	TEST	CONDITIONS	MIN	TYP†	MAX	UNIT
Vон	High-level output voltage	DOUT at R _L = $3 \text{ k}\Omega$ to GND,	DIN = GND	5	5.4		V
VOL	Low-level output voltage	DOUT at R _L = $3 \text{ k}\Omega$ to GND,	DIN = V _{CC}	-5	-5.4		V
lΗ	High-level input current	VI = VCC			±0.01	±1	μΑ
I _{IL}	Low-level input current	V _I at GND			±0.01	±1	μΑ
Γ.		V _{CC} = 3.6 V,	V _O = 0 V		±35	±60	
los	Short-circuit output current‡	V _C C = 5.5 V,	VO = 0 V		±35	±60	mA
r _O	Output resistance	V_{CC} , V+, and V- = 0 V,	V _O = ±2 V	300	10M		Ω
1	Output looks as surrent	FORCEOFF = GND	$V_O = \pm 12 \text{ V}, V_{CC} = 3 \text{ V to } 3.6 \text{ V}$			±25	
loff	Output leakage current	FURGEOFF = GND	$V_O = \pm 10 \text{ V}, V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$			±25	μΑ

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

	PARAMETER TEST CONDITIONS			MIN	TYP†	MAX	UNIT	
	Maximum data rate	C _L = 1000 pF,	$R_L = 3 k\Omega$,	See Figure 1	150	250		kbit/s
tsk(p)	Pulse skew§	$C_L = 150 \text{ pF to } 2500 \text{ pF},$	$R_L = 3 k\Omega$ to $7 k\Omega$,	See Figure 2		100		ns
CD(tr)	Slew rate, transition region	$V_{CC} = 3.3 \text{ V},$	$C_L = 150 \text{ pF to } 1000$) pF	6		30	V/uo
SR(tr)	(see Figure 1)	$R_L = 3 \text{ k}\Omega \text{ to } 7 \text{ k}\Omega$	C _L = 150 pF to 2500 pF		4		30	V/μs

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.

Pulse skew is defined as |tplh - tphl| of each channel of the same device.

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V \pm 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V \pm 0.5 V.



[‡] Short-circuit durations should be controlled to prevent exceeding the device absolute power-dissipation ratings, and not more than one output should be shorted at a time.

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ESD protection

TERMI	INAL	TEST COMPITIONS	TVD	LINUT
NAME NO.		TEST CONDITIONS	ITP	UNIT
DOUT	13	НВМ	±15	kV

RECEIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

	PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
Vон	High-level output voltage	I _{OH} = -1 mA	V _C C-0.6	V _{CC} -0.1		V
VOL	Low-level output voltage	I _{OL} = 1.6 mA			0.4	V
.,	Decition and an investigation of all and to an	V _{CC} = 3.3 V		1.6	2.4	.,
V _{IT+}	Positive-going input threshold voltage	V _{CC} = 5 V		1.9	2.4	V
	No matical region in put through all divides as	V _{CC} = 3.3 V	0.6	1.1		V
V _{IT} _	Negative-going input threshold voltage	V _{CC} = 5 V	0.8	1.4		V
V _{hys}	Input hysteresis (V _{IT+} - V _{IT-})			0.5		V
l _{off}	Output leakage current	FORCEOFF = 0 V		±0.05	±10	μΑ
rį	Input resistance	$V_I = \pm 3 \text{ V to } \pm 25 \text{ V}$	3	5	7	kΩ

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V \pm 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V \pm 0.5 V.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4)

	PARAMETER	TEST CONDITIONS	MIN TYP [†] MAX	UNIT
tPLH	Propagation delay time, low- to high-level output	C _L = 150 pF, See Figure 3	150	ns
tPHL	Propagation delay time, high- to low-level output	C _L = 150 pF, See Figure 3	150	ns
t _{en}	Output enable time	$C_L = 150 \text{ pF}, R_L = 3 \text{ k}\Omega, \text{See Figure 4}$	200	ns
tdis	Output disable time	$C_L = 150 \text{ pF}, R_L = 3 \text{ k}\Omega, \text{See Figure 4}$	200	ns
tsk(p)	Pulse skew [‡]	See Figure 3	50	ns

[†] All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V.

ESD protection

TERM	INAL	TEGT CONDITIONS	TVD	
NAME	TEST CONDITIONS		IYP	UNIT
RIN	8	НВМ	±15	kV



[‡] Pulse skew is defined as |tpLH - tpHL| of each channel of the same device.

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AUTO-POWERDOWN SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

	PARAMETER	TEST C	MIN	MAX	UNIT	
V _{T+(valid)}	Receiver input threshold for INVALID high-level output voltage	FORCEON = GND,	FORCEOFF = V _{CC}		2.7	٧
VT-(valid)	Receiver input threshold for INVALID high-level output voltage	FORCEON = GND,	FORCEOFF = V _{CC}	-2.7		V
VT(invalid)	Receiver input threshold for INVALID low-level output voltage	FORCEON = GND,	FORCEOFF = V _{CC}	-0.3	0.3	V
VOH	INVALID high-level output voltage	I _{OH} = -1 mA, FORCE FORCEOFF = V _{CC}	ON = GND,	V _{CC} -0.6		V
VOL	INVALID low-level output voltage	I _{OL} = 1.6 mA, FORCE FORCEOFF = V _{CC}	ON = GND,		0.4	V

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

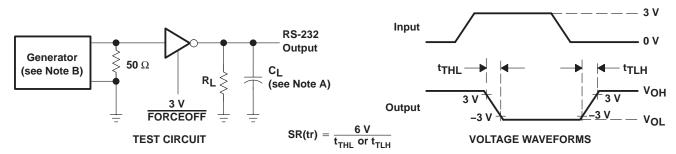
	PARAMETER	MIN	TYP†	MAX	UNIT
tvalid	Propagation delay time, low- to high-level output		1		μs
^t invalid	Propagation delay time, high- to low-level output		30		μs
ten	Supply enable time		100		μs

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.



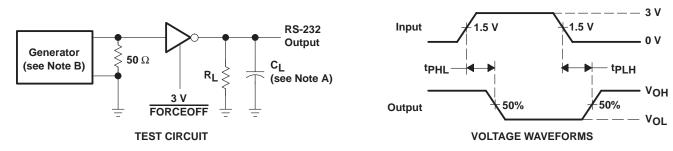
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PARAMETER MEASUREMENT INFORMATION



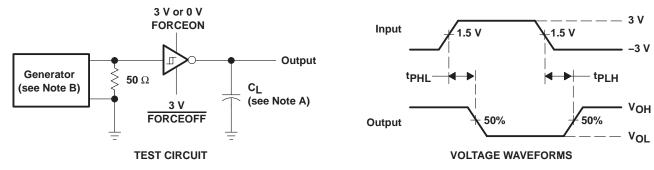
- NOTES: A. CL includes probe and jig capacitance.
 - B. The pulse generator has the following characteristics: PRR = 250 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_r \le 10$ ns. $t_f \le 10$ ns.

Figure 1. Driver Slew Rate



- NOTES: A. C_L includes probe and jig capacitance.
 - B. The pulse generator has the following characteristics: PRR = 250 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_f \le 10$ ns. $t_f \le 10$ ns.

Figure 2. Driver Pulse Skew



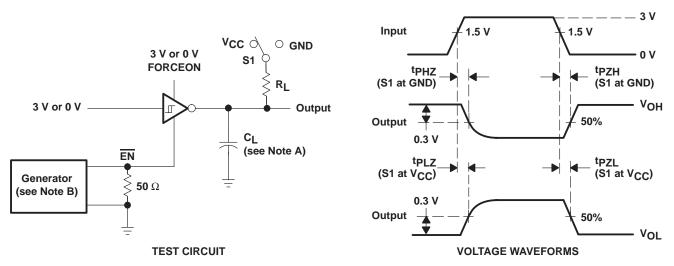
- NOTES: A. C_L includes probe and jig capacitance.
 - B. The pulse generator has the following characteristics: $Z_O = 50 \Omega$, 50% duty cycle, $t_\Gamma \le 10$ ns. $t_f \le 10$ ns.

Figure 3. Receiver Propagation Delay Times

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PARAMETER MEASUREMENT INFORMATION



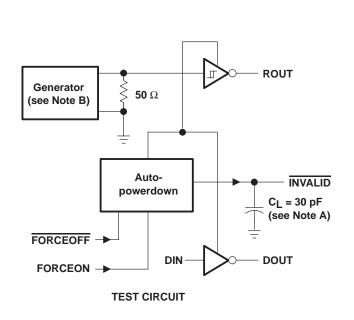
NOTES: A. C_L includes probe and jig capacitance.

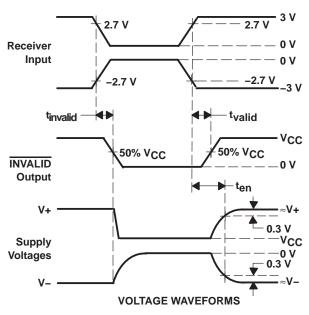
- B. The pulse generator has the following characteristics: $Z_O = 50 \ \Omega$, 50% duty cycle, $t_f \le 10 \ ns$, $t_f \le 10 \ ns$.
- C. tpLZ and tpHZ are the same as tdis.
- D. tpzL and tpzH are the same as ten.

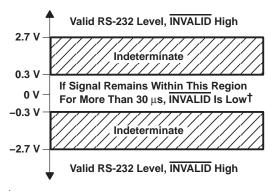
Figure 4. Receiver Enable and Disable Times



PARAMETER MEASUREMENT INFORMATION







† Auto-powerdown disables drivers and reduces supply current to 1 μA.

NOTES: A. C_L includes probe and jig capacitance.

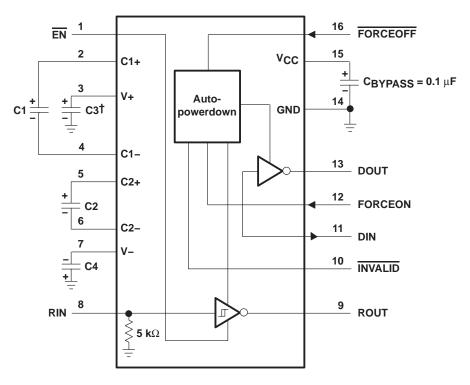
B. The pulse generator has the following characteristics: PRR = 5 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_\Gamma \le 10$ ns. $t_f \le 10$ ns.

Figure 5. INVALID Propagation Delay Times and Driver Enabling Time

3-V TO 5.5-V SINGLE-CHANNEL RS-232 LINE DRIVER/RECEIVER WITH $\pm 15\text{-kV}$ ESD PROTECTION

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APPLICATION INFORMATION



†C3 can be connected to VCC or GND.

NOTES: A. Resistor values shown are nominal.

B. Nonpolarized ceramic capacitors are acceptable. If polarized tantalum or electrolytic capacitors are used, they should be connected as shown.

V_{CC} vs CAPACITOR VALUES

VCC	C1	C2, C3, and C4
$\begin{array}{c} 3.3 \text{ V} \pm 0.3 \text{ V} \\ 5 \text{ V} \pm 0.5 \text{ V} \\ 3 \text{ V to } 5.5 \text{ V} \end{array}$	0.1 μF 0.047 μF 0.1 μF	0.1 μF 0.33 μF 0.47 μF

Figure 6. Typical Operating Circuit and Capacitor Values

PACKAGE OPTION ADDENDUM





PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
MAX3221CDB	ACTIVE	SSOP	DB	16	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3221CDBE4	ACTIVE	SSOP	DB	16	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3221CDBR	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3221CDBRG4	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
MAX3221CPW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3221CPWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3221CPWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3221CPWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3221IDB	ACTIVE	SSOP	DB	16	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3221IDBE4	ACTIVE	SSOP	DB	16	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3221IDBR	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3221IDBRE4	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3221IPW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3221IPWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3221IPWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3221IPWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



PACKAGE OPTION ADDENDUM

28-Sep-2005

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DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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